

stainable Growth with Innovative Integrated Electronic Systems

From super low power edge computing and car electronics to AI systems



3rd CIES

Technology

Forum

March 21 - 22, 2017

Registration

www.cies.tohoku.ac.jp/ 3rd forum/entry.html

Registration fee: Free Banquet fee: 7,000JPY Pre-registration deadline March 14, 2017

Tohoku University Center for Innovative Integrated Electronic Systems

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International Symposium

March 21, 2017

Station Conference Tokyo, Sapia Tower 5F, 501ABS 1-7-12 Marunouchi, Chiyoda-ku, Tokyo

Invited Speakers David Eggleston (GLOBALFOUNDRIES) Hideto Hidaka (Renesas Electronics) Hiroaki Honjo (Tohoku University) Seung H. Kang (Qualcomm) Masaaki Kuzuhara (Fukui University) Tetsuzo Ueda (Panasonic) Yoonjong Song (Samsung)

Chair

T. Endoh (Tohoku Univ.)

Committee S. Ikeda, K. Ito, M. Niwa,

H. Koike (Tohoku Univ.)

Secretariat T. Shinada, Y. Kadowaki (Tohoku Univ.)

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3rd CIES **Technology**

From super low power edge computing





International Symposium

and car electronics to AI systems <<< Registration desk open at 9:45am>>>

10:30-10:45Opening remarksTetsuo Endoh (Tohoku University)10:45-11:25Invited talk 1 What's Next for MRAM beyond Early Adopters?Seung H. Kang (Qualcomm)11:25-12:05Invited talk 2 Overview and challenge of current embedded STT-MRAMYoonjong Song (Samsung)12:05-12:45Invited talk 3 Material development in advanced STT-MRAM for non-volatile VLSI (Tohoku University)Hidroaki Honjo (Tohoku University)12:45-14:20LunchHideto Hidaka (Renesas Electronics)14:20-15:00Invited talk 4 How Future Embedded Mobility Meets IT - Embedded cyber-physical system designs revisit semiconductor technology -David Eggleston (GLOBALFOUNDRIES)15:00-15:40Invited talk 5 eMRAM: The march to manufacturingDavid Eggleston (GLOBALFOUNDRIES)15:40-16:00BreakInvited talk 6 GaN-based HEMT Technology for Low-loss and High-voltageMasaaki Kuzuhara (Fukui University)16:40-17:20Invited talk 7 Recent Progress in GaN Power DevicesTetsuzo Ueda (Panasonic)17:20-17:30Closing remarksShoji Ikeda (Tohoku University)18:00-19:30Banquet (Station Conference Tokyo, Sapia Tower 4F, 402ABCD)		<> Registration desk op	en at 9.43am///
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Inquiry

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